

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Sang-Geun Kim, Seung-Chul Ahn
Assignee: Samsung Electronics Co., Ltd
Title: Die Bonding Equipment (As Amended)
Serial No.: Unknown Filing Date: August 6, 2001
Examiner: Unknown Group Art Unit: Unknown
Docket No.: **AB-878-1D US**

San Jose, California
August 6, 2001

BOX NON-FEE AMENDMENT
COMMISSIONER FOR PATENTS
WASHINGTON, D. C. 20231

REQUEST TO AMEND DRAWINGS
UNDER 37 C.F.R. § 1.121

Sir:

Pursuant to 37 C.F.R. §1.121, Applicants respectfully request permission to amend
FIG. 6B as shown in red ink on the accompanying sheet.

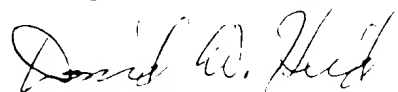
Should the Examiner have any questions concerning this request, the Examiner is
invited to call the undersigned at (408) 453-9200.

Express Mail Label No.

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August 6, 2001

Respectfully submitted,



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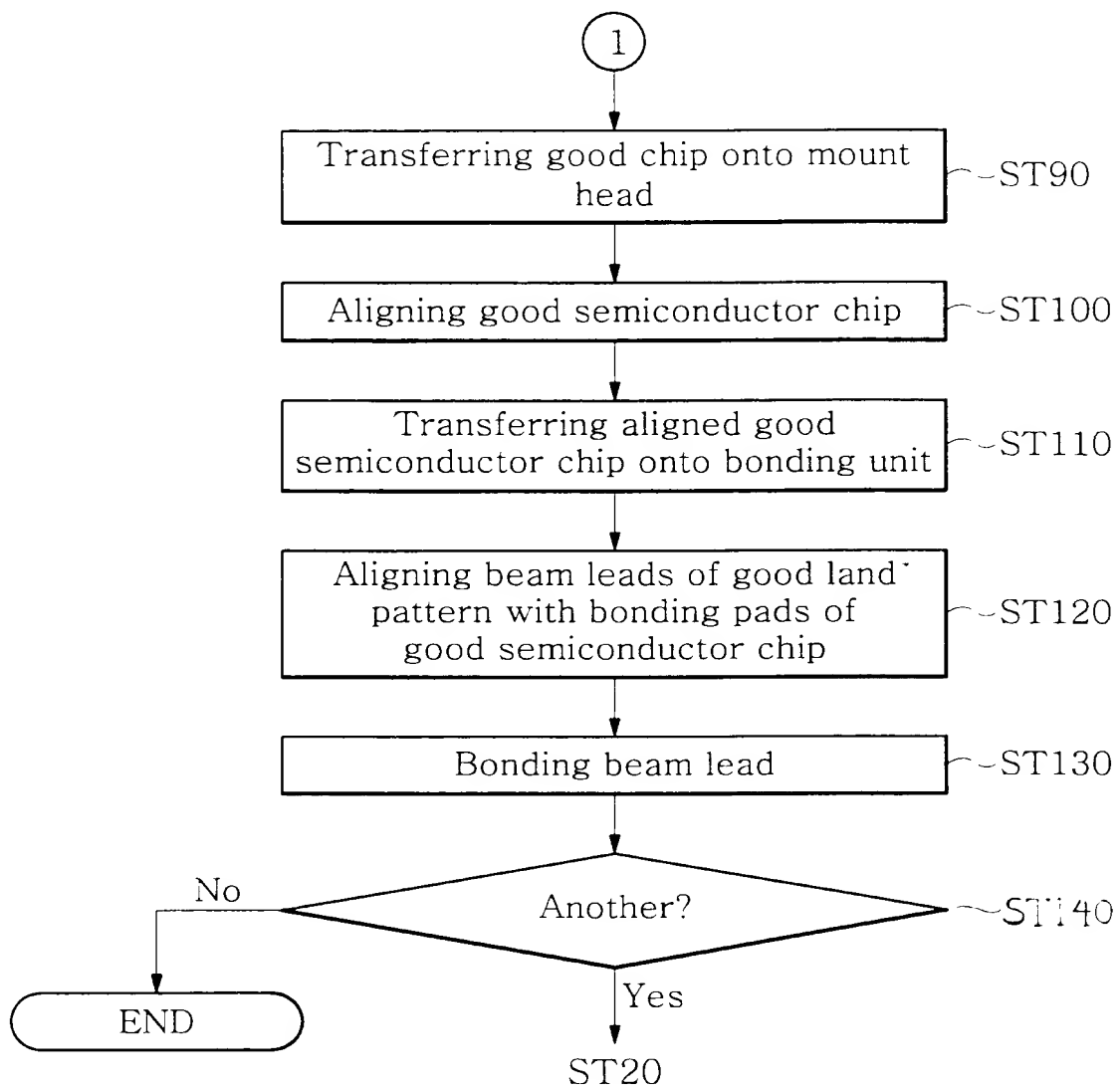


FIG. 6B